

Introduction

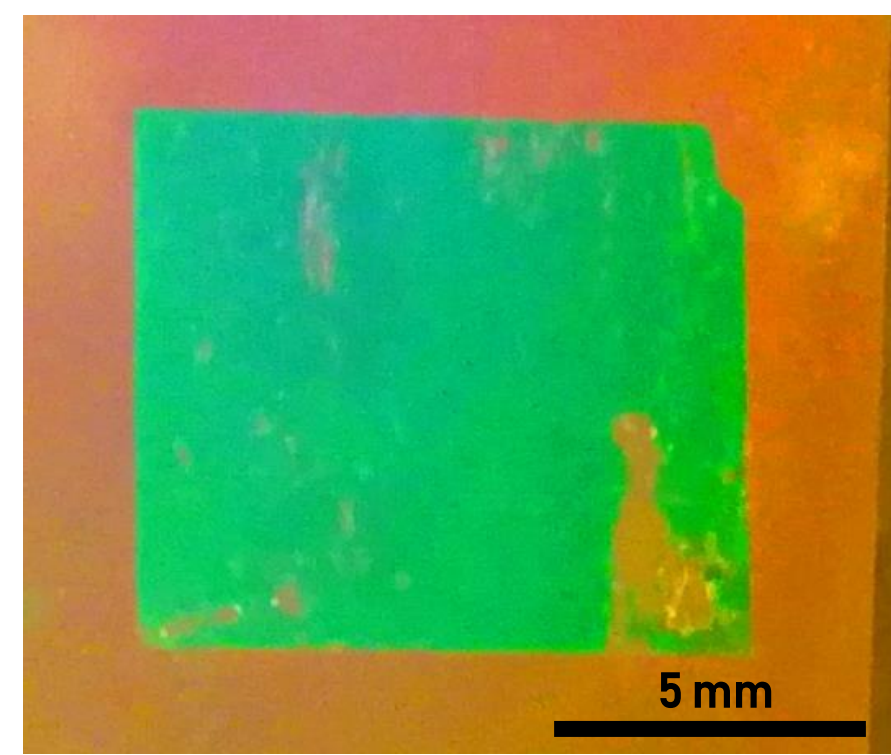
With the very active research in the 2D field lately, a wide variety of 2D materials on different growth substrate are obtainable. However, in most cases, a transfer toward another substrate is needed to have a functional device.

Here we present a method of transfer which works on almost every 2D/substrate combinations: the Spalling. This process is particularly interesting for 2D material which are very difficult to delaminate with the common wet polymer transfer.

Transfers results

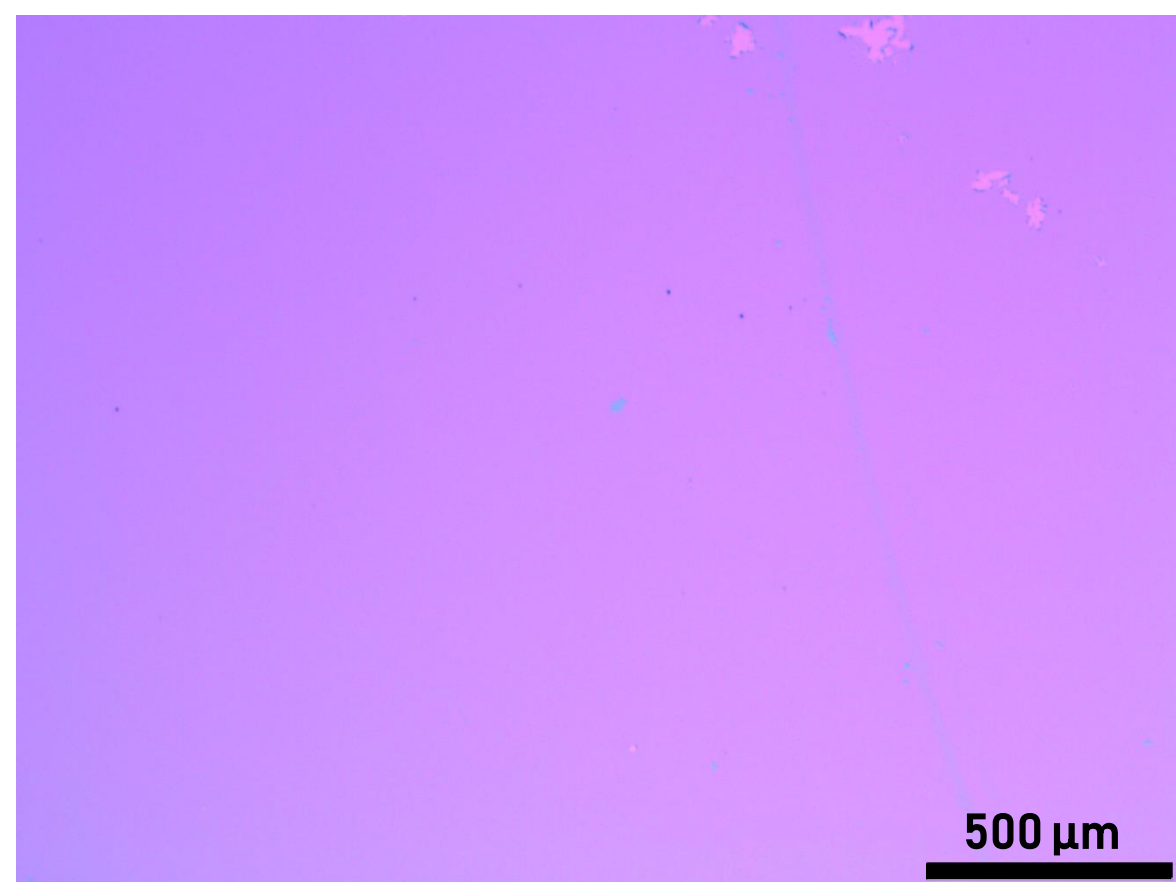
We studied our spalling transfer with two 2D materials : MoS₂ 3 to 6 layers grown on SiO₂ by the SDEP lab from CEA, LETI. And Graphene monolayer grown on sapphire by the Aixtron company.

With our process we succeed in transferring above 1 cm² of continuous layer of this two materials onto SiO₂ wafer. The wet transfer of MoS₂ is relatively easy and well-know and will serve as a reference to benchmark the spalling method. Whereas the spalling of graphene on sapphire is more interesting as there isn't a reliable method to transfer it yet.



Optical image of MoS₂ 3ML after spalling on SiO₂

Optical image of graphene monolayer after spalling on SiO₂



Delamination energy

The purpose of the strained metal layer deposited on the 2D material is to help with the delamination. The amount of energy this strained layer bring to the 2D can be calculated by the formulae of Shim et al:

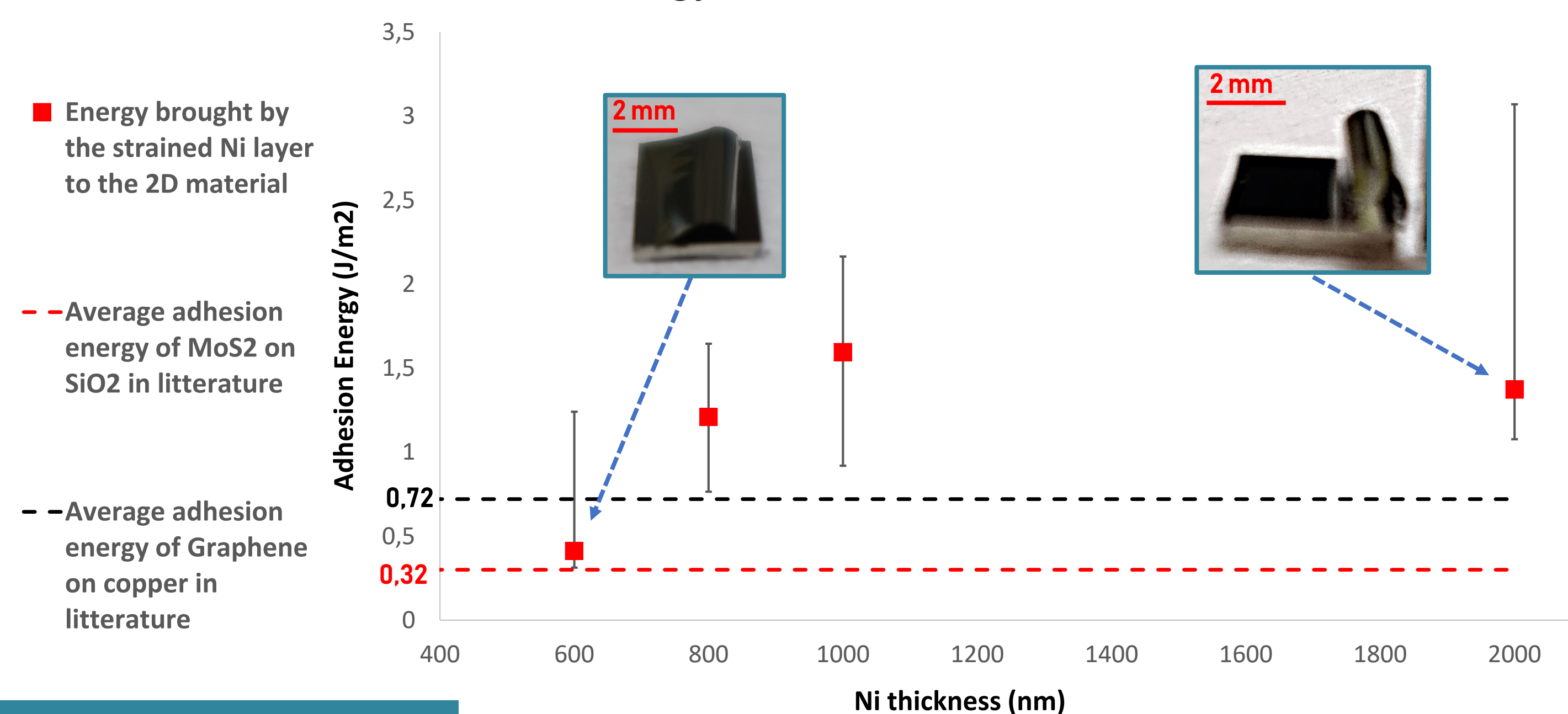
$$\Gamma_{\text{film-substrate}} = \frac{(1-\nu)H\sigma^2}{2Y}$$

Formulae proposed by Shim et al¹

Γ is the energy by surface, ν , H , σ and Y are respectively the Poisson factor, the thickness, the strain and the Young modulus of the metal layer.

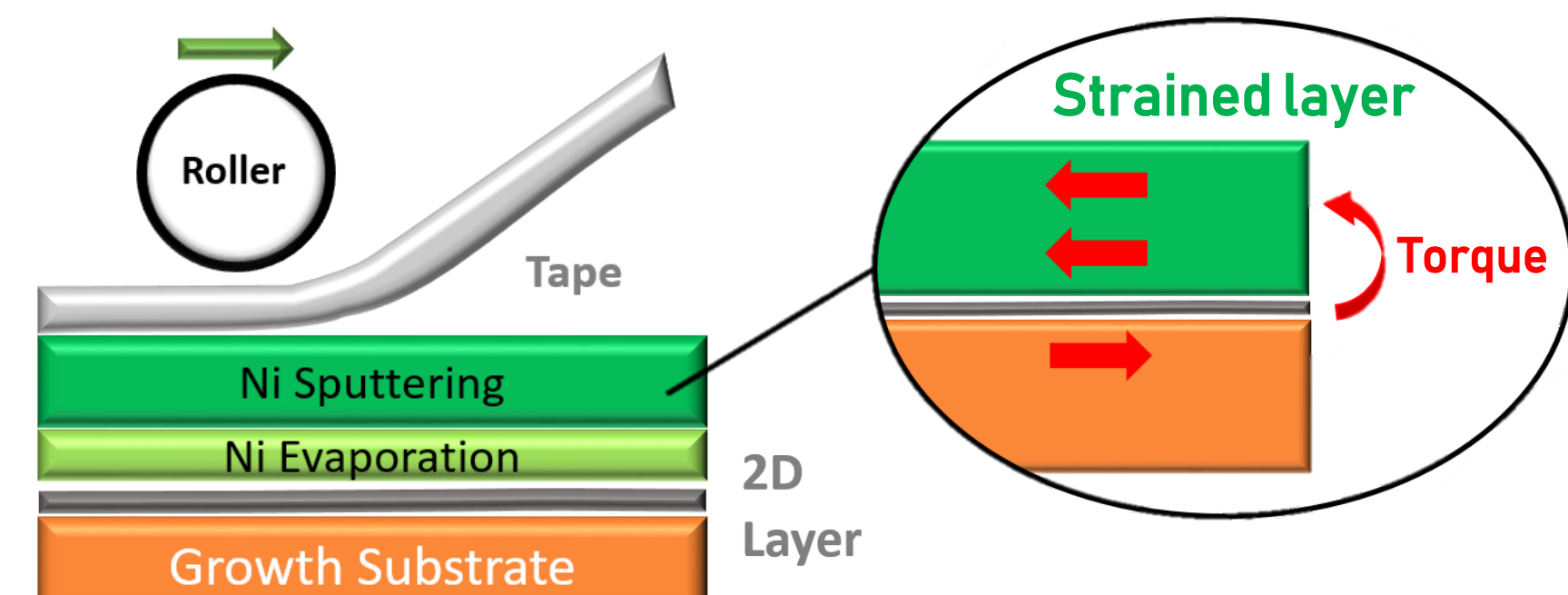
By increasing the thickness of the Ni layer until a spontaneous delamination is observed, we can deduce the adhesion energy 2D / substrate. No sample delaminated for the graphene, so $\Gamma > 1,5 \text{ J/m}^2$, while every samples delaminated for MoS₂, inducing : $\Gamma < 0,4 \text{ J/m}^2$

Adhesion energy versus the Nickel thickness

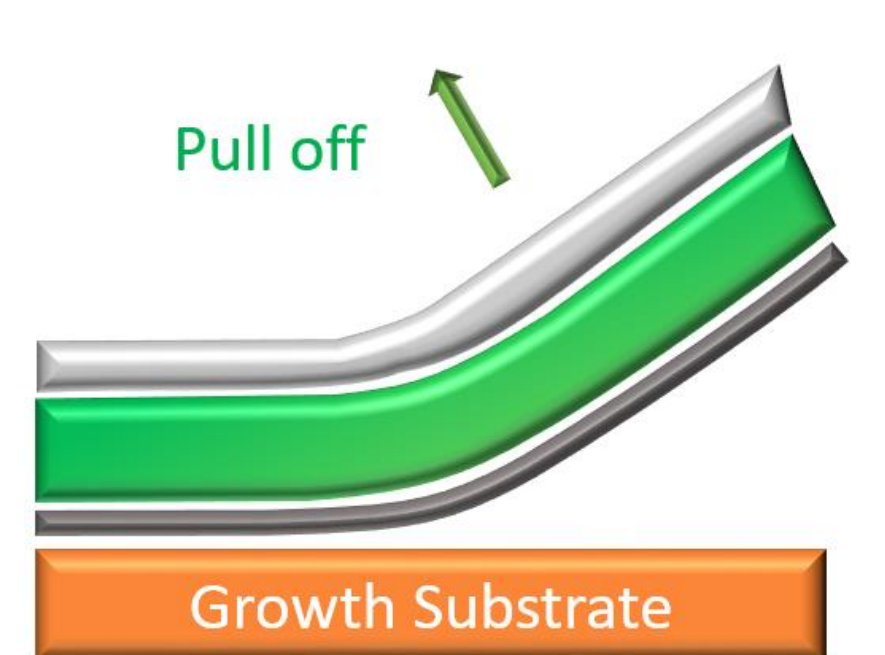


Spalling process

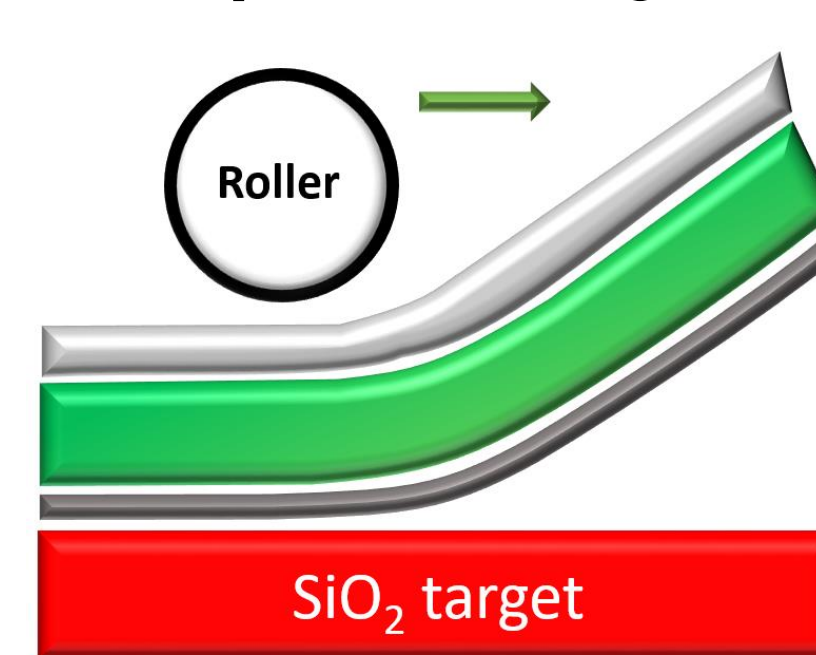
1) Metal deposition and tape set-up



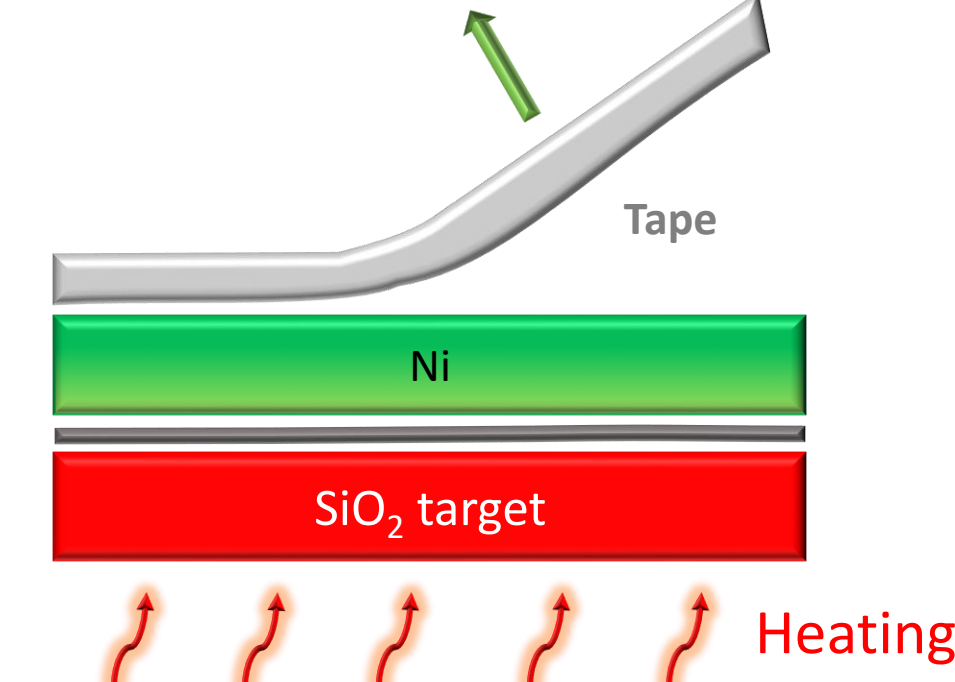
2) Peeling



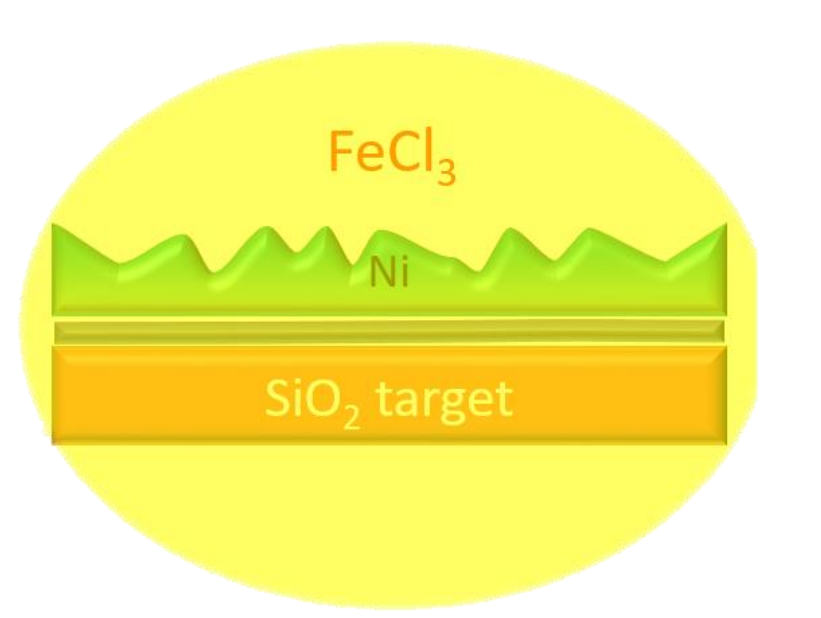
3) Report on target



4) Tape delamination



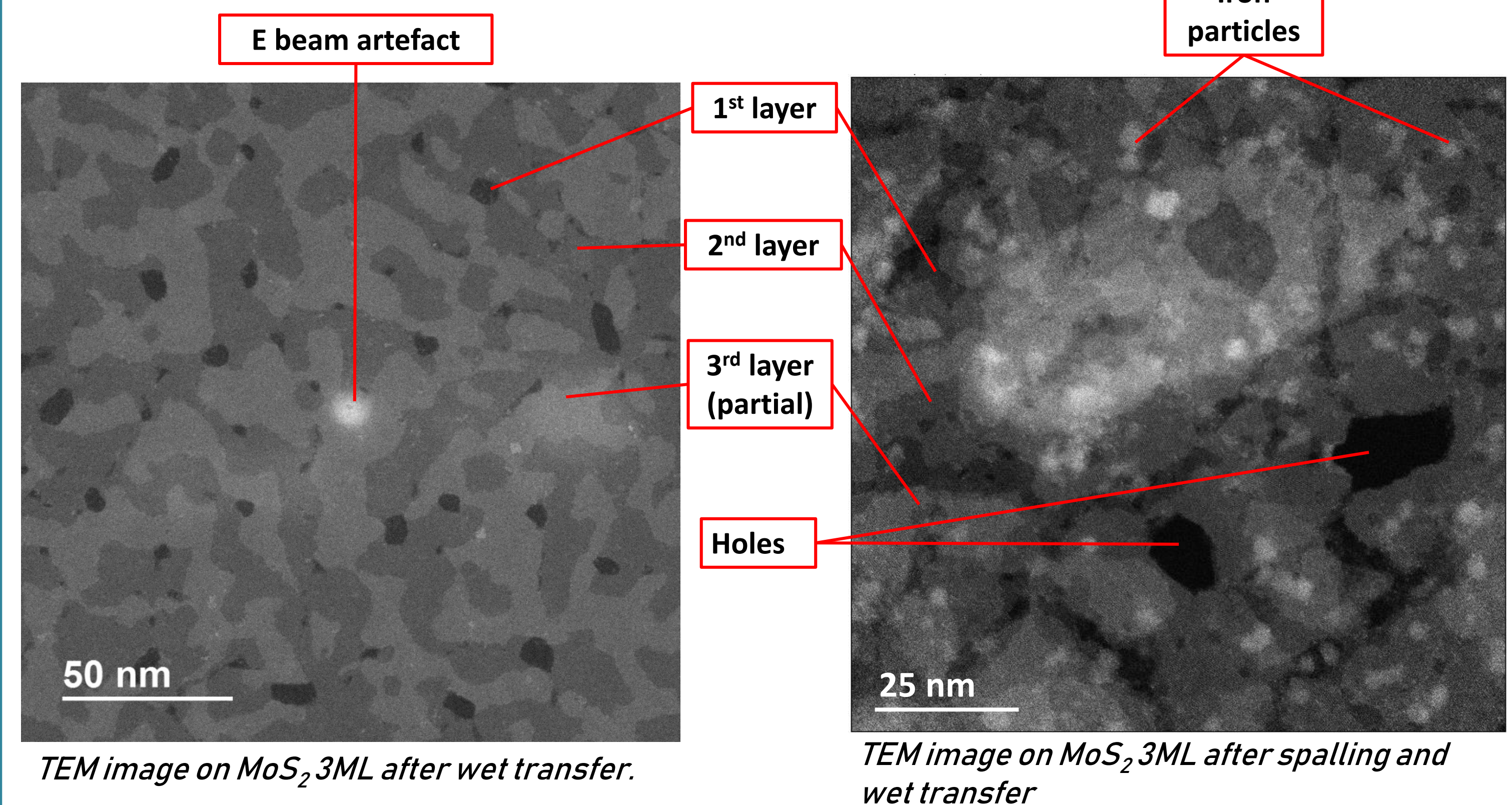
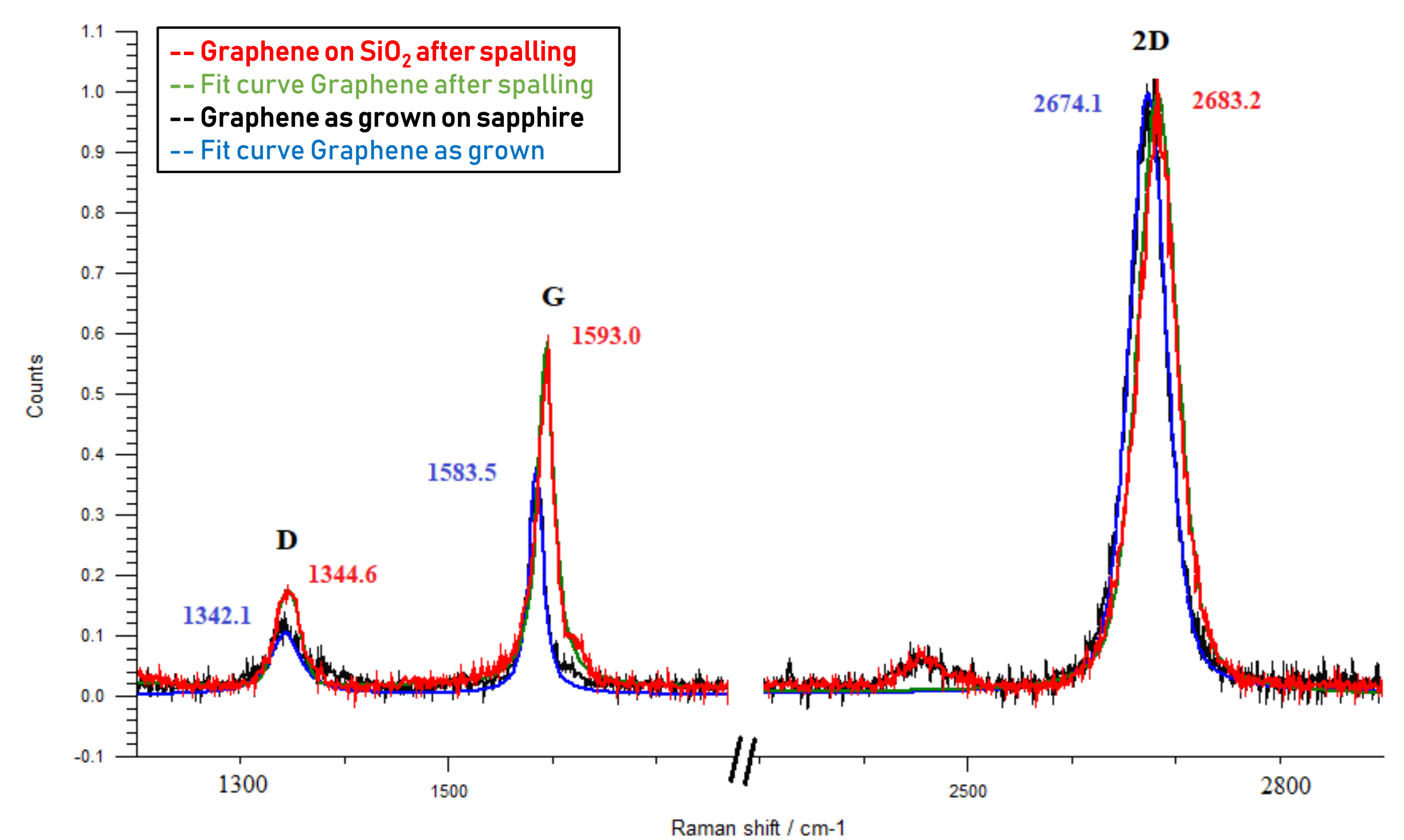
5) Nickel etching



Defects and Contamination

In order to investigate the contamination brought by the palling transfer, we made Raman and TEM analysis. With TEM we compared pristine MoS₂ and spalled MoS₂, both 3 layers thick. The report on the grids was done with the common wet process.

Normalized Raman spectra of Graphene as grown and after spalling



Conclusion

The spalling process enable the transfer of different 2D materials on the centimeter scale with the same protocol. Including 2D materials strongly bonded to their growth substrate, or for whom it doesn't exist a reliable delamination method yet, like graphene on sapphire. Moreover, the spalling shouldn't damaged the growth substrate, which could be re-used afterwards. However we detect some metallic contamination on the 2D materials after transfer. So more investigation is needed one the cleaning part after the etching of Nickel.

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REFERENCES

- 1 Shim, J. et al, *Science* 2018, vol362, pp. 665-670
- 2 Backes, C. et al. *2D Materials* 2020, vol 7

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